



2016 Spintronics Workshop on LSI

June 13, 2016, 19:00-21:45

Hilton Hawaiian Village, South Pacific Ballroom 1-2
Honolulu, Hawaii, USA



General Information

The 2016 Spintronics Workshop on LSI will be held at Hilton Hawaiian Village, Honolulu, Hawaii, on June 13, 2016, in conjunction with the VLSI Symposium on Technology as a Satellite Workshop of the 2016 VLSI Symposia. The workshop will focus on spintronics-based LSI technologies for high performance and ultra low power systems. Papers on current status, prospects and the remaining challenges in this field will be presented from invited speakers. The workshop is sponsored by Center for Innovative Integrated Electronic Systems (CIES), and Center for Spintronics Integrated Systems (CSIS), Tohoku University.

Registration

The workshop fee is free of charge, but registration is required.

The workshop was finished.
Thank you for your participation.

Program

19:00-19:15	Opening Remarks: Tetsuo Endoh (Tohoku University, Workshop Program Chair)	Chair: M. Niwa
19:15-19:40	Invited talk 1 Shunsuke Fukami (Tohoku University) Current Status and Future Outlook of Three-Terminal Spintronics Devices	
19:40-20:05	Invited talk 2 Song-Yun Kang (Tokyo Electron) STT-MRAM Market Status and Process Technology Update	
20:05-20:30	Invited talk 3 Junho Jeong (Samsung Electronics and Tohoku University) Developing status and prospect of MTJs patterning processes including damage recovering systems for the future spintronic industries	Chair: T. Endoh
20:30-20:55	Invited talk 4 David Eggleston (GLOBALFOUNDRIES) eMRAM: From Technology to Applications	
20:55-21:20	Invited talk 5 Chando Park (Qualcomm) Embedded STT-MRAM as an Enabler of Unified Memory Systems	
21:20-21:45	Invited talk 6 Takahiro Hanyu (Tohoku University) Challenge of Spintronics-Based Nonvolatile Logic-in-Memory VLSI Architecture towards the IoE Era	

Program Chair Tetsuo Endoh (Tohoku Univ.)

Program Committee H. S. Philip Wong (IEEE Executive Committee Chair of 2016 Symposia on VLSI Technology and Circuits)
Tadahiro Kuroda (JSAP Executive Committee Chair of 2016 Symposia on VLSI Technology and Circuits)
Hideo Ohno (Tohoku Univ.)
Takahiro Hanyu (Tohoku Univ.)
Masaaki Niwa (Tohoku Univ., JSAP Executive Committee Member of 2016 Symposia on VLSI Technology and Circuits)

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